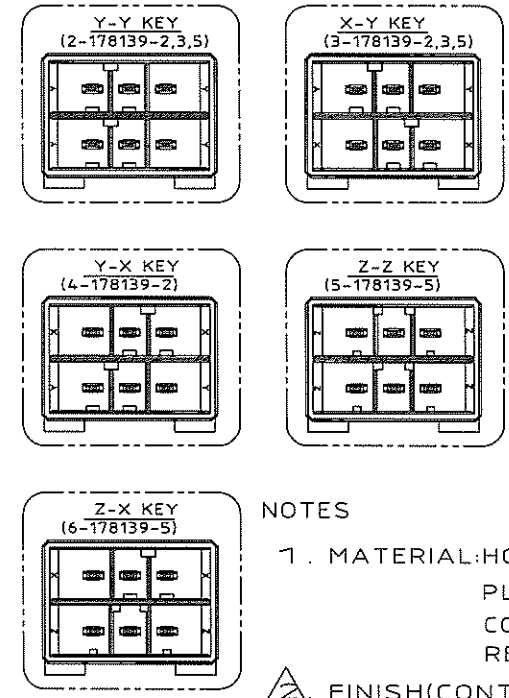
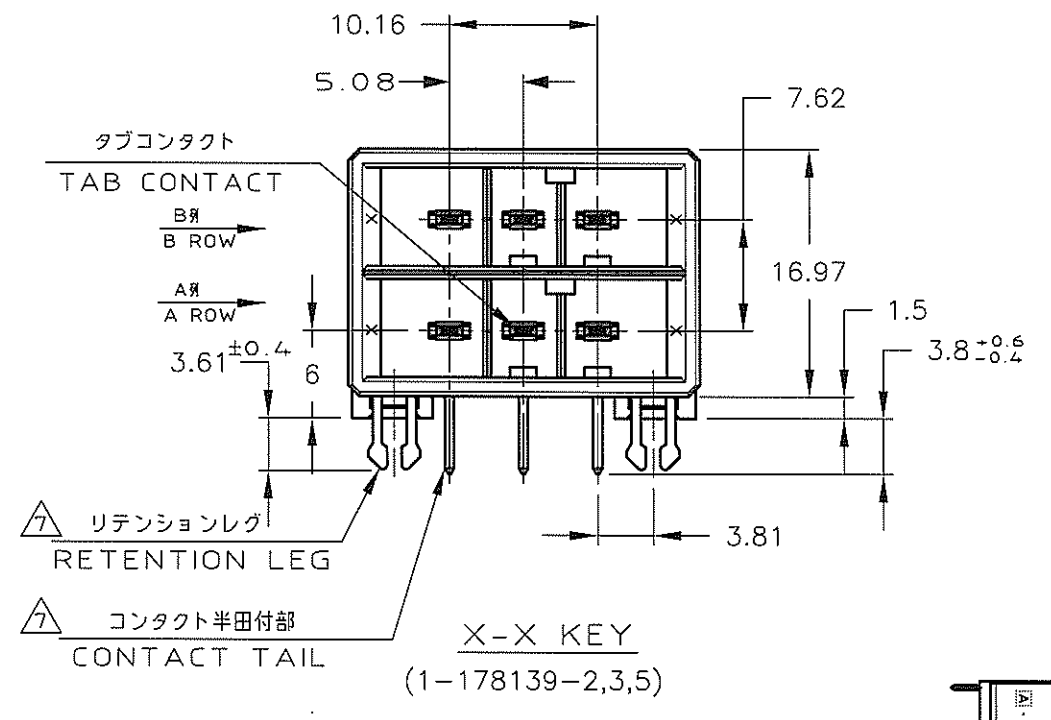
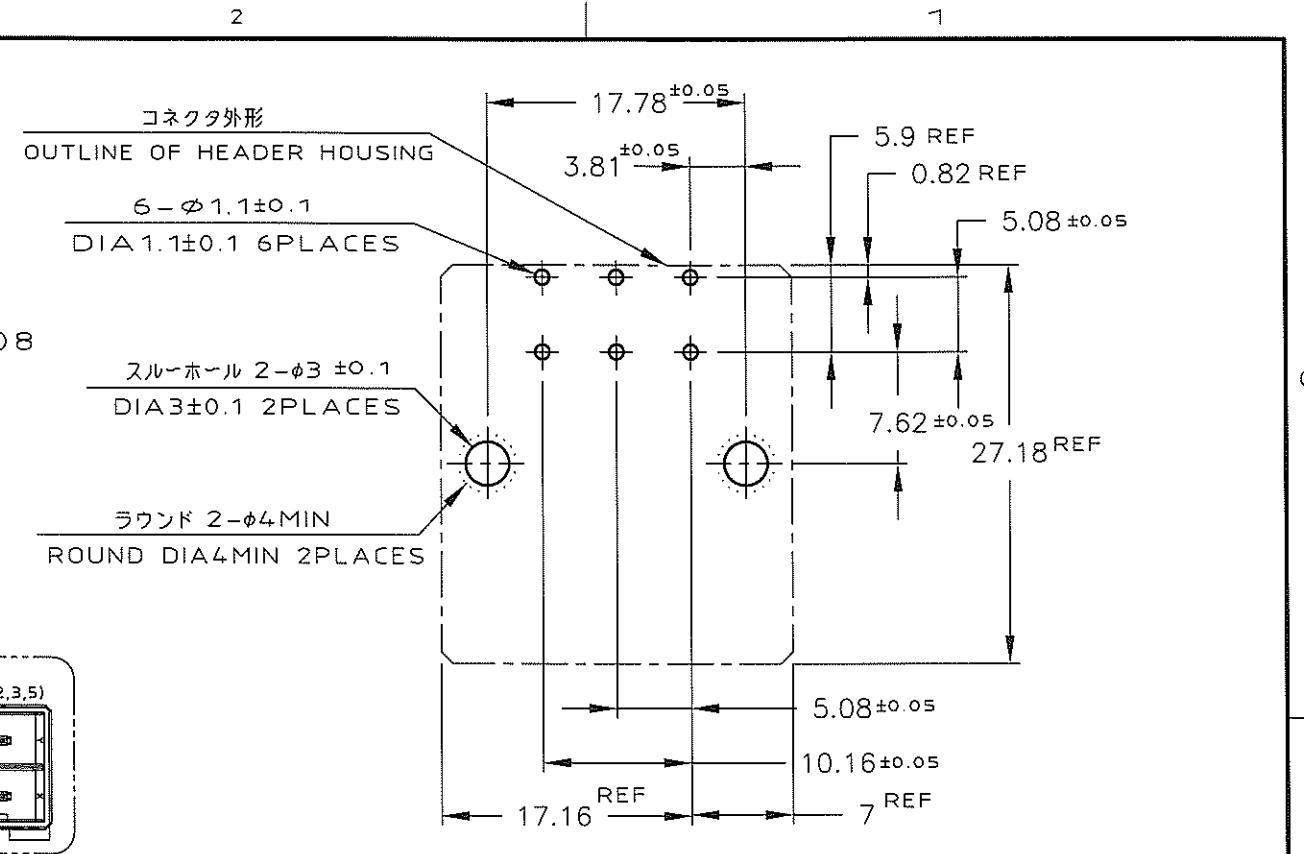
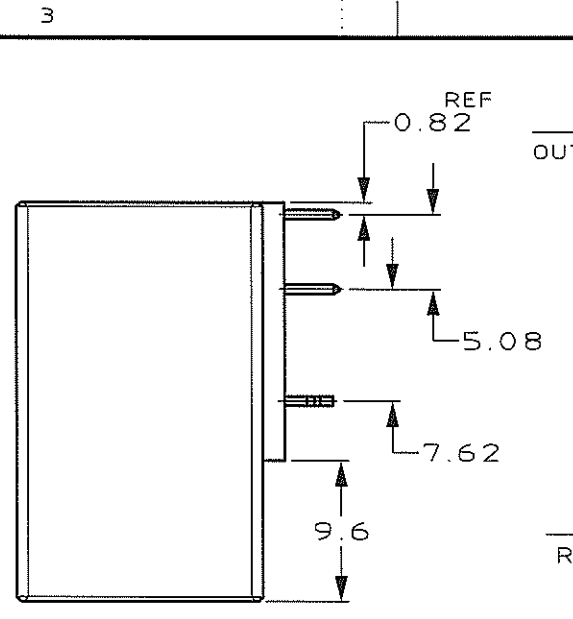
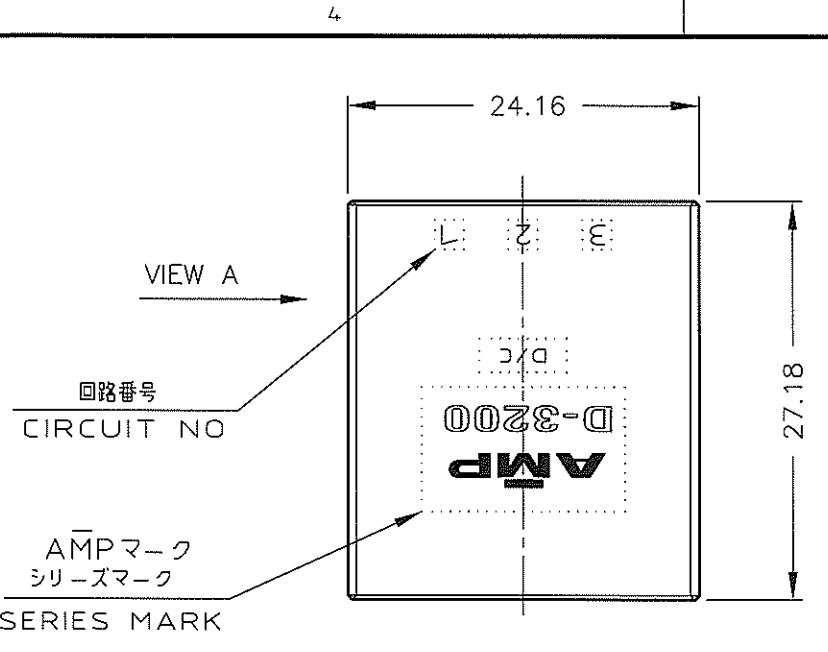


NUMBER 178139
 METRIC
 DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT
 PRINT DIST



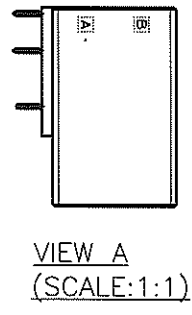
- NOTES
- MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER
CONTACT: COPPER ALLOY
RETENTION LEG: COPPER ALLOY
 - FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING
 - FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING
 - FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
 - FINISH (RETENTION LEG): TIN LEAD PLATED (CONTACT TAIL) OVER NICKEL
 - PRODUCT SPEC: 108-5349
 - FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

- 注記
- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂
コンタクト: 銅合金
リテンションレグ: 銅合金
 - めっき: コンタクト: 全面Ni下地
接触部: 0.38 μm MIN 金めっき
 - めっき: コンタクト: 全面Ni下地
接触部: 0.76 μm MIN 金めっき
 - めっき: コンタクト: 全面Ni下地
接触部: 2.0 μm MIN スズめっき
 - めっき: リテンションレグとコンタクト半田付部
ニッケル下地の土に半田めっき
 - 製品規格: 108-5349
 - めっき: リテンションレグとコンタクト半田付部
ニッケル下地の土にスズめっき

推奨基板取付け穴寸法
PC 基板厚: 1.6 ± 0.1 (非累積公差) (コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS: 1.6 ± 0.1 (NOT ACCUMULATE TOLERANCE) (CONNECTOR MOUNT SIDE)

△7	△4	1,2,3,5,6-178139-5
△7	△3	1,2,3-178139-3
△7	△2	1,2,3,4-178139-2
(FINISH)		製品番号 (PART NO.)



				WIRE RANGE		INSULATION DIA		NAME			
				mm ² (AWG -)		- mmφ		6 POS SINGLE ROW			
				MATERIAL SEE NOTE 注記参照		FINISH SEE NOTE 注記参照		HORIZONTAL HDR ASS'Y FOR DYNAMIC D-3200			
				E3 REVISED PER ECO-11-005030		DR. K.IKEDA 20/MAR/95		DE. K.IKEDA 20/MAR/95		一般公差 (GENERAL TOLERANCE)	
				LTR REVISION RECORD		CHK. S.MANABE 23/MAR/95		APP. S.MANABE 23/MAR/95		SIZE LOC NUMBER	
				DR		HMR		14APR 11		A3 J C-178139	
				DR		CHK		DATE		SCALE REV. SHEET	
				DR		CHK		DATE		2-1 E3 1 OF 1	

(CUSTOMER DRAWING) 顧客用図面



Mouser Electronics

Authorized Distributor

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[1-178139-3](#)